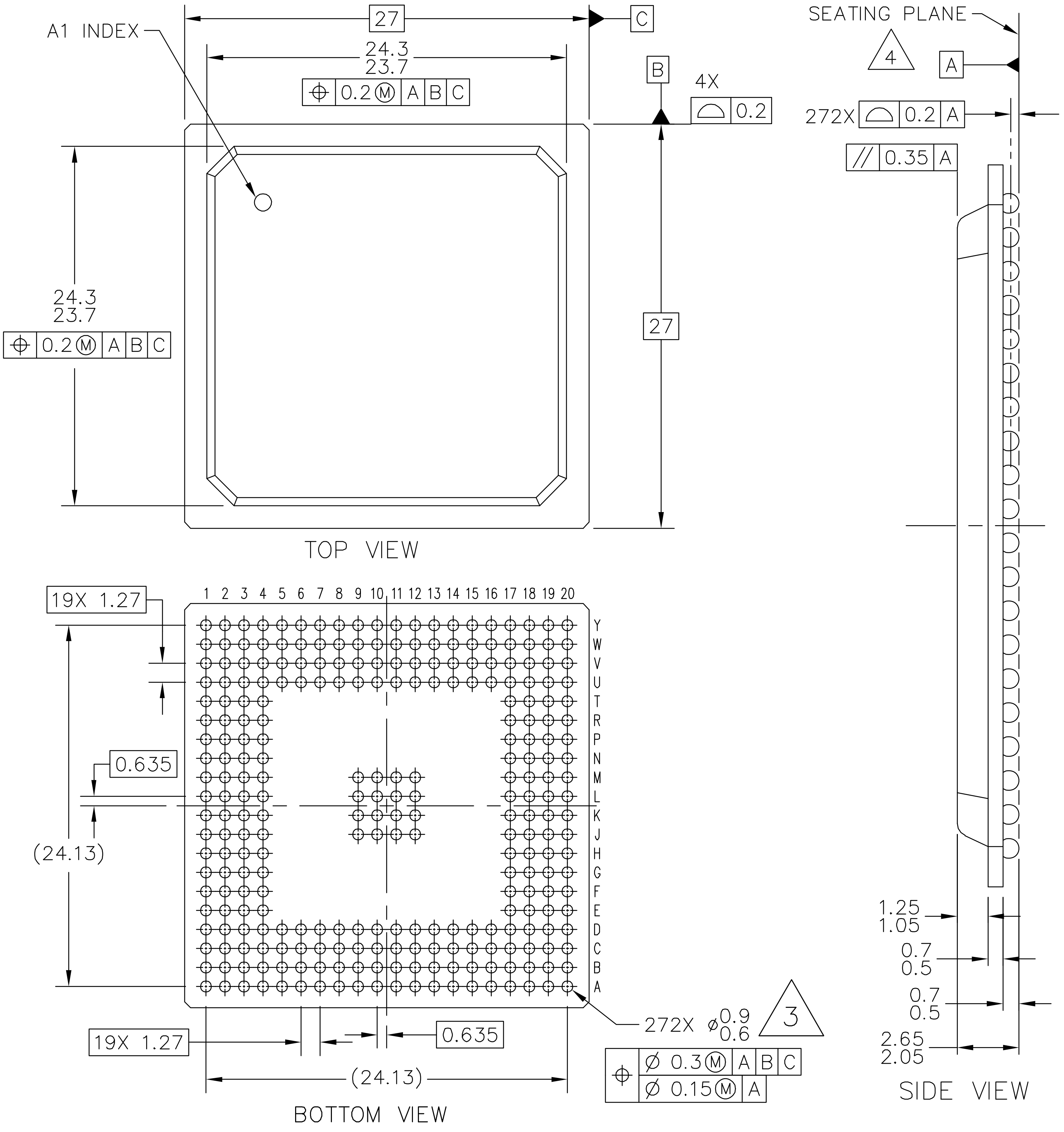

MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE:
272 I/O, PBGA
27 X 27 PKG,
1.27MM PITCH (OMPAC)

DOCUMENT NO: 98ASS23712W

REV: G

CASE NUMBER: 1135A–02

16 JUN 2006

STANDARD: JEDEC MS–034 BAL–2

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PACKAGE CODES:
   5065 – 2 LAYER 272 PBGA
   5047 – 4 LAYER 272 TEPBGA
   5192 – 4 LAYER 272 TEPBGA PGE

MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

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